



DATA SHEET

ANTI-SULFURATED CHIP RESISTORS AF122 (4Pin/2R) / AF124 (8Pin/4R) / AF164 (8Pin/4R)

5%, 1% sizes 2 × 0402, 4 × 0402, 4 × 0603 RoHS compliant

Product specification –May 29, 2015 V.2



YAGEO Phícomp

Chip Resistor Surface Mount

SCOPE

This specification describes AF122/AF124/AF164 (convex)series chip resistor arrays with lead-free terminations made by thick film process.

APPLICATIONS

- Industrial Equipment
- Power Application
- Networking Application
- High-end Computer & Multimedia Electronics in high sulfur environment

FEATURES

- RoHS compliant
 - Products with lead free terminations meet RoHS requirements
 - Pb-glass contained in electrodes
 - Resistor element and glass are exempted by RoHS
- Reducing environmentally hazardous wastes
- High component and equipment reliability
- Saving of PCB space
- None forbidden-materials used in products/production
- Halogen Free Epoxy
- Moisture sensitivity level: MSL I

ORDERING INFORMATION - GLOBAL PART NUMBER & 12NC

Both part numbers are identified by the series, size, tolerance, packing type, temperature coefficient, taping reel and resistance value.

YAGEO BRAND ordering code

AF

GLOBAL PART NUMBER (PREFERRED)

AF XX X - X X X XX XXXX L

(T٦	(2)	(3) (4) (5) (6) ((7)	۱ ۱
(1)	(4)) (3)(4) (3) (0) (1)

(I) SIZE

12 = 0402 × 2 (0404)	
12 = 0402 × 4 (0408)	
16 = 0603 × 4 (0612)	

(2) NUMBER OF RESISTORS

s
s

4 = 4 resistors

(3) TOLERANCE

F = ±1%

 $J = \pm 5\%$ (for Jumper ordering, use code of J)

(4) PACKAGING TYPE

R = Paper taping reel

(5) TEMPERATURE COEFFICIENT OF RESISTANCE

- = Base on spec

(6) TAPING REEL

07 = 7 inch dia. Reel 13 = 13 inch dia. Reel

(7) RESISTANCE VALUE

There are $2\sim4$ digits indicated the resistor value. Letter R/K/M is decimal point, no need to mention the last zero after R/K/M, e.g. IK2, not IK20.

Detailed resistance rules show in table of "Resistance rule of global part number".

(8) DEFAULT CODE

Resistance rule o number	f global part
Resistance code rule	Example
0R	0R = Jumper
XRXX (Ι to 9.76 Ω)	IR = Ι Ω IR5 = I.5 Ω 9R76 = 9.76 Ω
XXRX (10 to 97.6 Ω)	l0R = 10 Ω 97R6 = 97.6 Ω
XXXR (100 to 976 Ω)	100R = 100 Ω
XKXX (Ι to 9.76 ΚΩ)	IK = 1,000 Ω 9K76 = 9760 Ω
XM (Ι MΩ)	IM = 1,000,000 Ω

ORDERING EXAMPLE

The ordering code of a AF122 convex chip resistor array, value 1,000 Ω with ±5% tolerance, supplied in 7-inch tape reel is: AF122-JR-071KL.

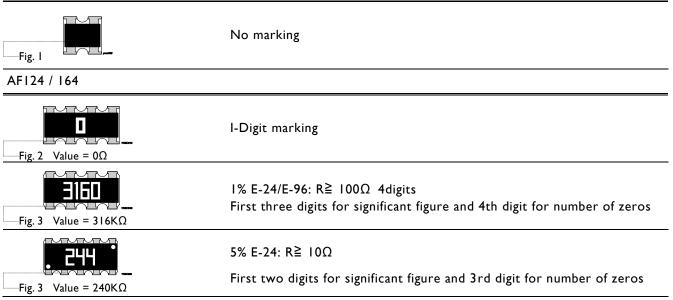
NOTE

- All our R-Chip products meet RoHS compliant. "LFP" of the internal 2D reel label mentions "Lead Free Process"
- On customized label, "LFP" or specific symbol printed and the optional "L" at the end of GLOBAL PART NUMBER

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MARKING

AFI22

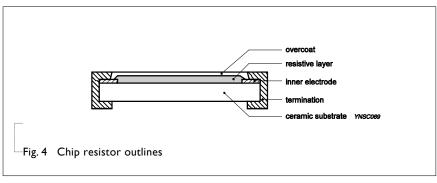


For further marking information. please refer to data sheet "Chip resistors marking".

CONSTRUCTION

The resistor is constructed on top of a high-grade ceramic body. Internal metal electrodes are added on each end to make the contacts to the thick film resistive element. The composition of the resistive element is a noble metal imbedded into a glass and covered by a second glass to prevent environment influences. The resistor is laser trimmed to the rated resistance value. The resistor is covered with a protective epoxy coat, finally the external terminations (matte tin on Nibarrier) are added as shown in Fig.4.

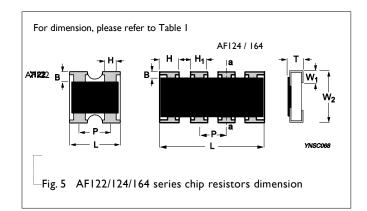
OUTLINES



DIMENSIONS

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Table I			
TYPE	AF122	AFI24	AFI64
B (mm)	0.24±0.10	0.25±0.15	0.35±0.15
H (mm)	0.30+0.10/-0.05	0.45±0.05	0.65±0.05
H₁ (mm)		0.30±0.05	0.50±0.15
P (mm)	0.67±0.05	0.50±0.05	0.80±0.05
L (mm)	1.00±0.10	2.00±0.10	3.20±0.15
T (mm)	0.30±0.10	0.45±0.10	0.60±0.10
W _I (mm)	0.25±0.10	0.30±0.15	0.30±0.15
W ₂ (mm)	1.00±0.10	1.00±0.10	1.60±0.15



Chip Resistor Surface Mount

SCHEMATIC

For dimension, please refer to Fig. 5 and Table 1 AF12	4 3 R1 R2 1 2	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$
Fig. 6 Equivalent circuit diagram	R1 = R2	RI=R2=R3=R4

AF

ELECTRICAL CHARACTERISTICS

Table 2							
CHARACTERISTICS		AFI22		AFI24		A	AF164
Operating Temperature Range	-55	°C to +I25 °C	-55	°C to +155 °C	-55	°C to +I	55 °C
Rated Power		1/16 W		1/16 W		I	/16W
Maximum Working Voltage		50 V		25 V			50V
Maximum Overload Voltage		100 V		50 V			100V
Dielectric Withstanding Voltage		100 V		100 V			100V
Resistance Range	5% (E24) I% (E24/E96)	Ω to ΜΩ 0 Ω to ΜΩ	5% (E24) 1% (E24/E96)	Ω to ΜΩ Ω to ΜΩ	5%(E24) 1% (E24/E96)		ο Ι Μ Ω ο Ι Μ Ω
U U	Ju	mper < 50 m Ω	Ju	mper < 50 m Ω	J	umper <5	i0 mΩ
Townsom time Coofficient	$I \Omega \leq R < I0 \Omega$	±250 ppm/°C	$I \Omega \leq R < I0 \Omega$	±250 ppm/°C		±250 ppm/'	
Temperature Coefficient	$\textbf{I0} \ \Omega \leq \textbf{R} \leq \textbf{I} \ \textbf{M} \Omega$	±200 ppm/°C	$\textbf{I0}\ \Omega \leq \textbf{R} \leq \textbf{I}\ \textbf{M}\Omega$	±200 ppm/°C			
luma an Critania	Rated Current	0.5 A	Rated Current	I.0 A	Rated	Current	1.0A
Jumper Criteria	Maximum Current	1.0 A	Maximum Current	2.0 A	Maximun	n Current	2.0A

FOOTPRINT AND SOLDERING PROFILES

For recommended footprint and soldering profiles, please refer to data sheet "Chip resistors mounting".

PACKING STYLE AND PACKAGING QUANTITY

Table 3 Packing style	and packaging quantity			
PACKING STYLE	REEL DIMENSION	AF122	AFI24	AF164
Paper Taping Reel (R)	7" (178 mm)	10,000 units	10,000 units	5,000 units
	I 3" (330 mm)	50,000 units	40,000 units	20,000 units

NOTE

I. For paper tape and reel specification/dimensions, please refer to data sheet "Chip resistors packing".



Chip Resistor Surface Mount

AF

FUNCTIONAL DESCRIPTION

POWER RATING

AF122 / AF124 / AF164 rated power at 70 $^\circ\text{C}$ is 1/16 W

RATED VOLTAGE

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

$V = \sqrt{(PXR)}$

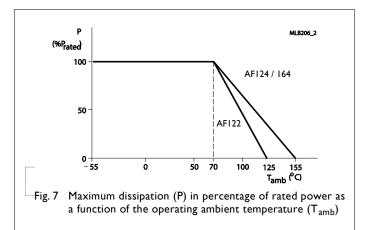
or max. working voltage whichever is less

Where

V=Continuous rated DC or AC (rms) working voltage (V)

P=Rated power (W)

R=Resistance value (Ω)





Chip Resistor Surface Mount AF

TESTS AND REQUIREMENTS

Life/	MIL-STD-202-method 108	I,000 hours at 70±5 °C applied RCWV	±(2%+0.05 Ω)
Operational Life/	IEC 60115-1 4.25.1	1.5 hours on, 0.5 hour off, still air required	<100 m Ω for Jumper
Endurance	JIS C 5202-7.10		
High Temperature Exposure	MIL-STD-202-method 108	I,000 hours at maximum operating temperature depending on specification, unpowered	±(1%+0.05 Ω) <50 mΩ for Jumper
		No direct impingement of forced air to the parts	
		Tolerances: 125±3 °C	
Moisture	MIL-STD-202-method 106	Each temperature / humidity cycle is defined	±(2%+0.05 Ω)
Resistance		at 8 hours (method 106F), 3 cycles / 24 hours for 10d with 25 °C / 65 °C 95% R.H, without steps 7a & 7b, unpowered	<100 m Ω for Jumper
		Parts mounted on test-boards, without condensation on parts	
		Measurement at 24±2 hours after test conclusion	
Thermal Shock	MIL-STD-202-method 107	-55/+125 °C	±(1%+0.05 Ω)
		Note: Number of cycles required is 300. Devices mounted	<50 m Ω for Jumper
		Maximum transfer time is 20 seconds. Dwell time is 15 minutes. Air – Air	
Short Time	IEC60115-14.13	2.5 times RCWV or maximum overload	±(2%+0.05 Ω)
Overload		voltage whichever is less for 5 sec at room	<50 m Ω for Jumper
		temperature	No visible damage
Board Flex/	IEC60115-1 4.33 Device mounted on PCB test board as		±(1%+0.05 Ω)
Bending		described, only I board bending required	<50 m Ω for Jumper
		3 mm bending	No visible damage
		Bending time: 60±5 seconds Ohmic value checked during bending	



Chip Resistor Surface Mount

SERIES 122/124/164 (RoHS Compliant)

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Solderability			
- Wetting	J-STD-002B test B	Electrical Test not required	Well tinned (≥95% covered)
		Magnification 50X	No visible damage
		SMD conditions:	
		I st step: method B, aging 4 hours at 155 °C	
		dry heat	
		2^{nd} step: leadfree solder bath at 245±3 °C	
		Dipping time: 3±0.5 seconds	
- Leaching	STD-002B test D	Leadfree solder, 260 °C, 30 seconds immersion time	No visible damage
- Resistance to	IEC 60115-1 4.18	Condition B, no pre-heat of samples	±(1%+0.05Ω)
Soldering Heat	MIL-STD-202 Method 210	Leadfree solder, 260 °C, 10 seconds	<50 m Ω for Jumper
		immersion time	No visible damage
		Procedure 2 for SMD: devices fluxed and cleaned with isopropanol	-
FOS	ASTM-B-809-95	Sulfur (saturated vapor) 1000 hours, 90±2°C, unpowered.	±(1.0%+0.05Ω)
-	ASTM-B-809-95*	– Sulfur 750 hours, 105°C, unpowered	±(4.0%+0.05Ω)
	*Modified	· · · ·	



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REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 2	May 29,2015	-	- Add in AFI64
Version I	Aug. 15, 2014	-	- Update AF124 dimensions
Version 0	Oct. 02, 2013	-	- First issue of this specification

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